

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT								
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT								
<b>CONVEYING PARTY DATA</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Makoto Tada</td> <td>09/03/2007</td> </tr> <tr> <td>Chi-Pin CHOU</td> <td>09/03/2007</td> </tr> <tr> <td>Li-Shua SUN</td> <td>09/03/2007</td> </tr> </tbody> </table>		Name	Execution Date	Makoto Tada	09/03/2007	Chi-Pin CHOU	09/03/2007	Li-Shua SUN	09/03/2007
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Makoto Tada	09/03/2007								
Chi-Pin CHOU	09/03/2007								
Li-Shua SUN	09/03/2007								
<b>RECEIVING PARTY DATA</b>									
<b>Name:</b>	HIWIN MIKROSYSTEM CORP.								
<b>Street Address:</b>	NO. 1, 6TH RD., TAICHUNG INDUSTRY PARK								
<b>City:</b>	TAICHUNG								
<b>State/Country:</b>	TAIWAN								
<b>Postal Code:</b>	407								
<b>PROPERTY NUMBERS Total: 1</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11850676</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11850676				
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Application Number:	11850676								
<b>CORRESPONDENCE DATA</b>									
<b>Fax Number:</b>	(361)579-9966								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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<b>ATTORNEY DOCKET NUMBER:</b>	CFP-3768 (C-275)								
<b>NAME OF SUBMITTER:</b>	BANGER SHIA								

Total Attachments: 3  
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**500348302**

**PATENT  
 REEL: 019787 FRAME: 0055**

**OP \$40.00 11850676**



**ASSIGNMENT      DEED**

**ASSIGNOR:**

MAKOTO TADA

2-8-23, HONCHOU, HATOGAYA-SHI, SAITAMA, 334-0002,

JAPAN

CHOU, CHI-PIN

NO. 1, 6<sup>TH</sup> ROAD, TAICHUNG INDUSTRIAL PARK, TAICHUNG 407,

TAIWAN, R.O.C.

SUN, LI-SHUA

NO. 1, 6<sup>TH</sup> ROAD, TAICHUNG INDUSTRIAL PARK, TAICHUNG 407,

TAIWAN, R.O.C.

**ASSIGNEE:**

HIWIN MIKROSYSTEM CORP.

NO. 1, 6<sup>TH</sup> RD., TAICHUNG INDUSTRY PARK, TAICHUNG,

TAIWAN, R.O.C.

Whereas, MAKOTO TADA & CHOU, CHI-PIN & SUN, LI-SHUA

whose address is set forth above (hereinafter referred to as "Assignor", consideration of payment to it of the sum of Ten U.S. Dollars (U.S.\$10.00) and for other good and valuable consideration, receipt and sufficiency of which are acknowledged hereby; received from

HIWIN MIKROSYSTEM CORP., whose address is set forth above (hereinafter referred to as "Assignee");

Assignor has sold, assigned, and conveyed and hereby does evidence such sale, assignment and conveyance unto said Assignee, its successors and/or assigns, Assignor's

entire right, title and interest —

(1) In and to an invention entitled \_\_\_\_\_

**POSITIVE LOAD ALIGNMENT MECHANISM**

as described in United States Patent Application Serial No. \_\_\_\_\_, filed on \_\_\_\_\_; which issued into United States Letters Patent No. \_\_\_\_\_ on \_\_\_\_\_, including the right to recover for past infringements thereof.

(2) In and to said Application for Letters Patent and said Letters Patent No. \_\_\_\_\_ which issued \_\_\_\_\_ on said Application and any and all other applications for letters patent of the United States of America (including renewal, divisional, continuation, continuation-in-part, substitute and reissue applications) based upon said invention, including extensions and reissues, if any, to the full ends of the terms for which said Letters Patent of the United states has been granted.

(3) In and to all applications for said invention, now or hereafter filed in countries foreign to the United States of America, and in and to any and all letters patent granted on said applications to the full ends of the terms for which said Letters Patent may be granted.

Assignor further covenants and agrees that it has not executed and will not execute any documents in conflict herewith, and it further agrees that it will at any time upon request by Assignees execute and deliver any and all papers that may be necessary or desirable to perfect title to said invention, Application for Letters Patent, and the Letters Patent to Assignees, and if Assignees desires to file one or more divisional, continuation, continuation-in-part, or substitute applications of or for said Letters Patent of the United States of America, or to secure a reissue or extension of such Letters Patent, or to file a disclaimer relating thereto, Assignors will upon request by Assignees sign all papers, make all rightful oaths and do all lawful acts requisite of it for such reissue or extension, or the procuring thereof, and for the filing of such disclaimer, but at the expense of Assignees, its successors and/or assigns.

Assignor further agrees that it will at any time upon request by Assignee communicate to Assignee any facts relating to said invention and Letters Patent or the history thereof, know to Assignor and cause its agent(s) to testify to the same in any interference or any litigation when requested so to do by Assignee.

And the Commissioner of Patents and Trademarks of the United States of America and comparable officials in countries foreign to the United States of America to record and/or issue said Letters Patent, and the like to Assignee as assignee of Assignor's entire right, title and interest therein.

Signed at TAICHUNG, TAIWAN this 3 day  
of SEP. 2007.

Assignor:

By : Makoto Tada      Sun Li Shua      Chou Chi-Pin

Name : MAKOTO TADA & CHOU,CHI-PIN & SUN,LI-SHUA

Title : INVENTOR(S)

Date : SEP. 3, 2007

Witness:

Signature: \_\_\_\_\_

Name :

Address :

Date: